ABSTRACT

Method for encapsulating, in a mould, an electronic component having a number of laterally projecting elongated connecting elements situated next to one another in one plane, said connecting elements being without metallic through connection and having a certain mutual pitch (P_L), width (W_L) and height (T_L), and with the insertion of two films, each having a predetermined thickness (T_{FT} and T_{FB}, respectively), a deformable film being used and the encapsulation being carried out under conditions which are such that, during the process, the condition

$$C \cdot T_L - \left\{ 1 - \frac{W_L}{P_L} \right\} \leq (T_{TF} + T_{BF})$$

at the position of the clamping edges of the matrix parts, while

$C \geq 2.5$.

This Sheet Has Been Replaced

